

# SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

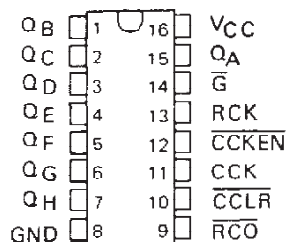
SDLS003

D2632, JANUARY 1981 — REVISED MARCH 1988

- 8-Bit Counter with Register
- Parallel Register Outputs
- Choice of 3-State ('LS590) or Open-Collector ('LS591) Register Outputs
- Guaranteed Counter Frequency: DC to 20 MHz

SN54LS590, SN54LS591 . . . J OR W PACKAGE  
SN74LS590, SN74LS591 . . . N PACKAGE

(TOP VIEW)



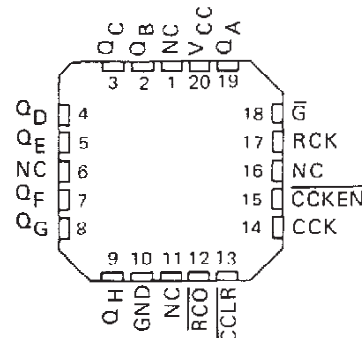
## description

These devices each contain an 8-bit binary counter that feeds an 8-bit storage register. The storage register has parallel outputs. Separate clocks are provided for both the binary counter and storage register. The binary counter features a direct clear input  $\overline{\text{CCLR}}$  and a count enable input  $\overline{\text{CCKEN}}$ . For cascading, a ripple carry output  $\overline{\text{RCO}}$  is provided. Expansion is easily accomplished for two stages by connecting  $\overline{\text{RCO}}$  of the first stage to  $\overline{\text{CCKEN}}$  of the second stage. Cascading for larger count chains can be accomplished by connecting  $\overline{\text{RCO}}$  of each stage to CCK of the following stage.

Both the counter and register clocks are positive-edge triggered. If the user wishes to connect both clocks together, the counter state will always be one count ahead of the register. Internal circuitry prevents clocking from the clock enable.

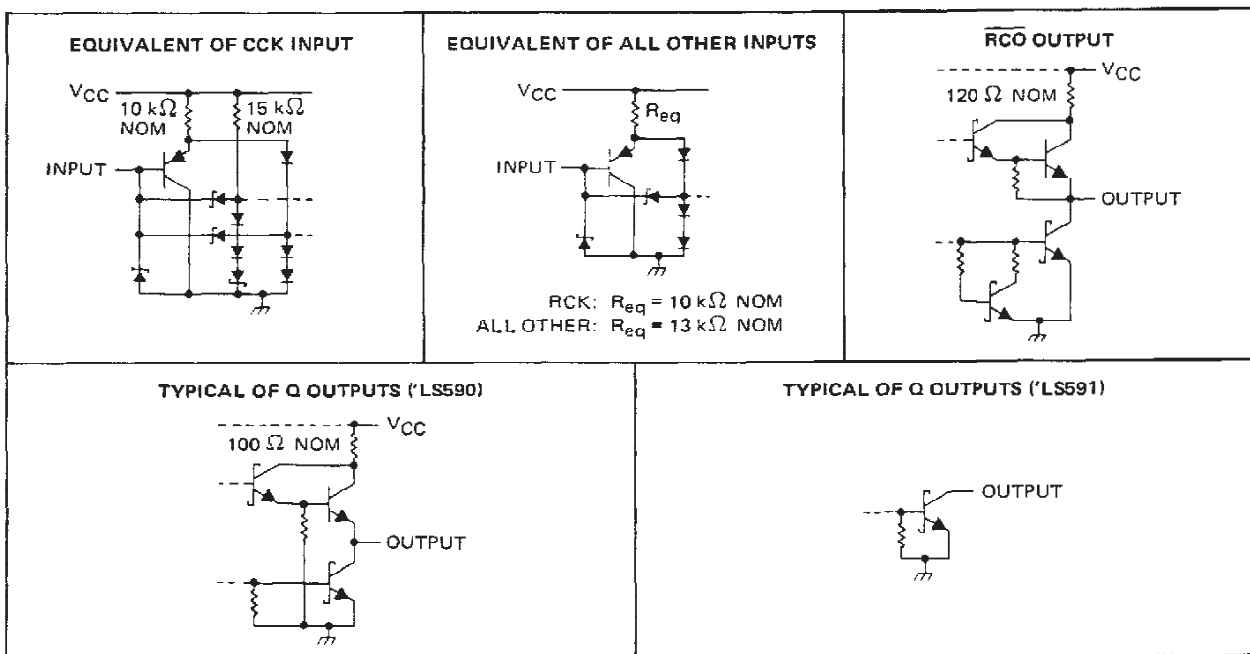
SN54LS590, SN54LS591 . . . FK PACKAGE

(TOP VIEW)



## schematics of inputs and outputs

NC - No internal connection



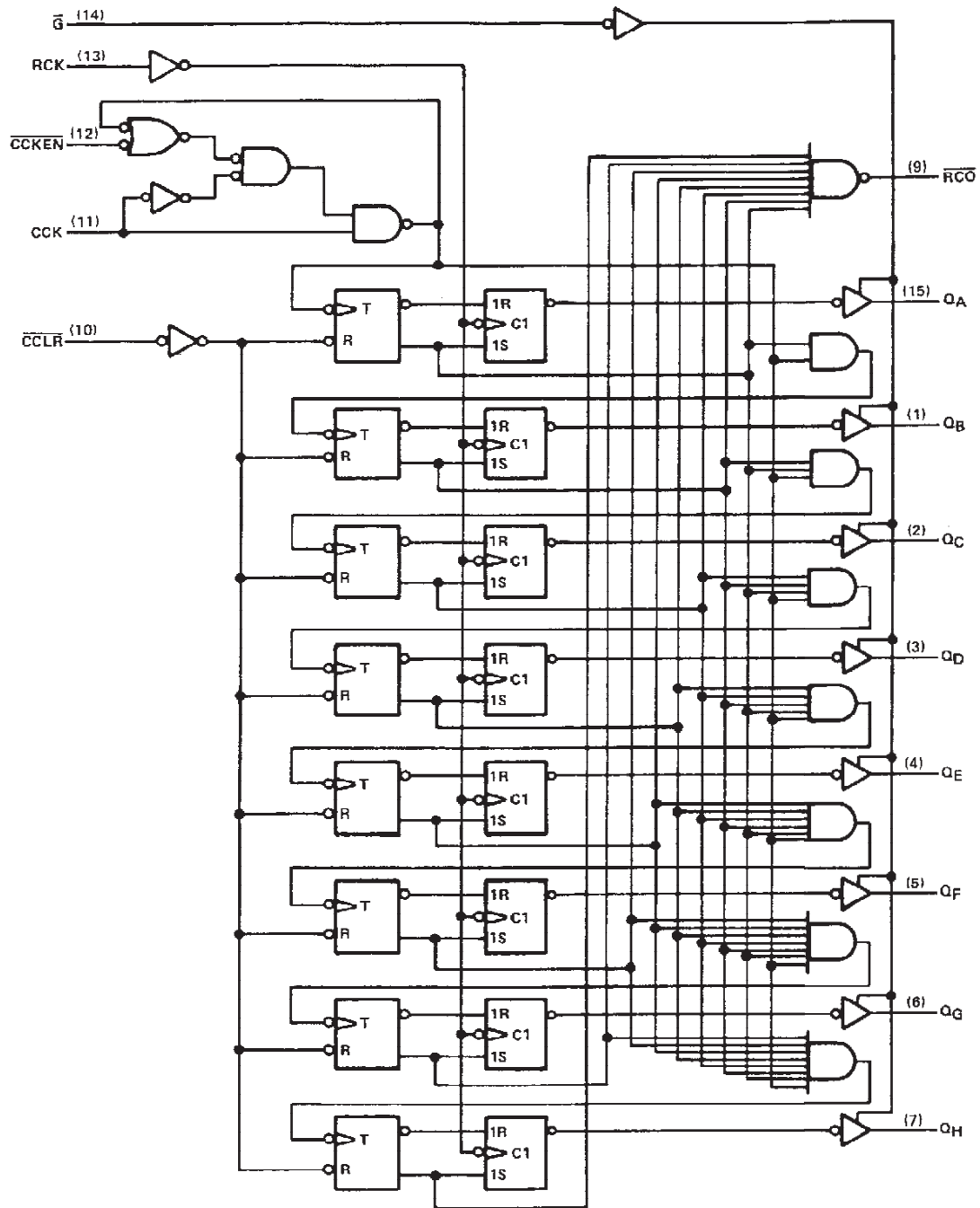
PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TEXAS  
INSTRUMENTS

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**SN54LS590, SN54LS591, SN74LS590, SN74LS591**  
**8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS**

logic diagram (positive logic)



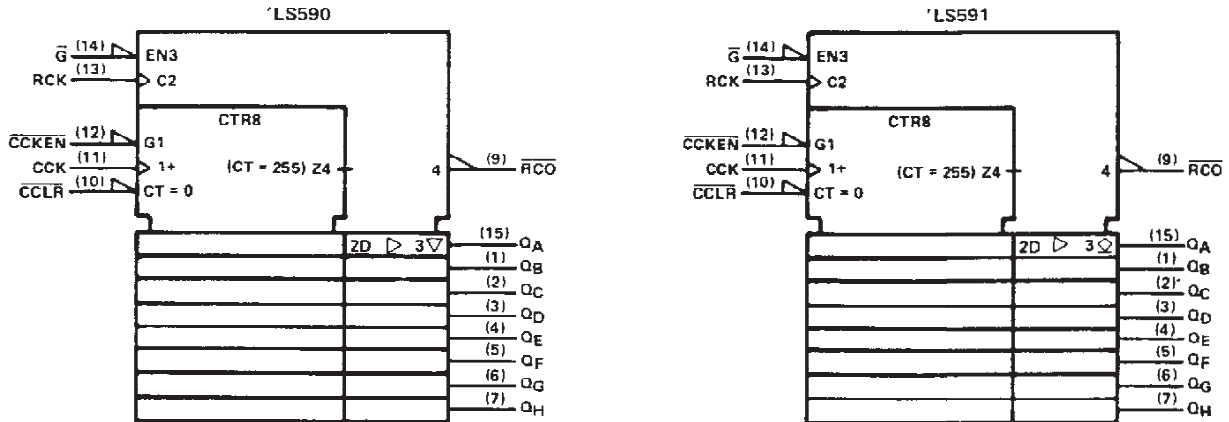
Pin numbers shown are for J, N and W packages.

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# SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

logic symbols†



†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.  
Pin numbers shown are for J, N, and W packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

|  |  |
|--|--|
| Supply voltage, $V_{CC}$ (see Note 1)                      | 7 V  |
| Input voltage  | 7 V  |
| Off-state output voltage                                   | 5.5 V  |
| Operating free-air temperature range: SN54LS590, SN54LS591 | $-55^{\circ}\text{C}$ to $125^{\circ}\text{C}$ |
| SN74LS590, SN74LS591                                       | $0^{\circ}\text{C}$ to $70^{\circ}\text{C}$    |
| Storage temperature range                                  | $-65^{\circ}\text{C}$ to $150^{\circ}\text{C}$ |

NOTE 1: Voltage values are with respect to the network ground terminal.

## recommended operating conditions

|             |                                  | SN54LS'                       |     |     | SN74LS' |     |      | UNIT               |
|-------------|----------------------------------|-------------------------------|-----|-----|---------|-----|------|--------------------|
|             |                                  | MIN                           | NOM | MAX | MIN     | NOM | MAX  |                    |
| $V_{CC}$    | Supply voltage                   | 4.5                           | 5   | 5.5 | 4.75    | 5   | 5.25 | V                  |
| $V_{IH}$    | High-level input voltage         | 2                             |     |     | 2       |     |      | V                  |
| $V_{IL}$    | Low-level input voltage          |                               |     | 0.7 |         |     | 0.8  | V                  |
| $V_{OH}$    | High-level output voltage        | Q, 'LS591 only                |     | 5.5 | 5.5     |     |      | V                  |
| $I_{OH}$    | High-level output current        | RCO                           |     | -1  | -1      |     |      | mA                 |
|             |                                  | Q, 'LS590 only                |     | -1  | -2.6    |     |      |                    |
| $I_{OL}$    | Low-level output current         | RCO                           |     | 8   | 16      |     |      | mA                 |
|             |                                  | Q                             |     | 12  | 24      |     |      |                    |
| $f_{CCK}$   | Counter clock frequency          | 0                             |     | 20  | 0       |     | 20   | MHz                |
| $f_{RCK}$   | Register clock frequency         | 0                             |     | 25  | 0       |     | 25   | MHz                |
| $t_w(CCK)$  | Duration of counter clock pulse  | 25                            |     |     | 25      |     |      | ns                 |
| $t_w(CCLR)$ | Duration of counter clear pulse  | 20                            |     |     | 20      |     |      | ns                 |
| $t_w(RCK)$  | Duration of register clock pulse | 20                            |     |     | 20      |     |      | ns                 |
| $t_{su}$    | Setup time                       | CCKEN low before CCK ↑        |     | 20  | 20      |     |      | ns                 |
|             |                                  | CCLR inactive before CCK ↑    |     | 20  | 20      |     |      |                    |
|             |                                  | CCK before RCK ↑ (see Note 2) |     | 40  | 40      |     |      |                    |
| $t_h$       | Hold time                        | CCKEN low after CCK ↑         |     | 0   | 0       |     |      | ns                 |
| $T_A$       | Operating free-air temperature   | -55                           |     | 125 | 0       |     | 70   | $^{\circ}\text{C}$ |

NOTE 2: This setup time ensures the register will see stable data from the counter outputs. The clocks may be tied together in which case the register state will be one clock pulse behind the counter.

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# SN54LS590, SN54LS591, SN74LS590, SN74LS591

## 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER         |                            |   | TEST CONDITIONS†                                   |                          | SN54LS* |       | SN74LS* |       | UNIT |
|-------------------|----------------------------|---|--|--------------------------|---------|-------|---------|-------|------|
|                   |                            |   |  |                          | MIN     | TYP‡  | MAX     | MIN   |      |
| V <sub>IK</sub>   |                            |   | V <sub>CC</sub> = MIN,                             | I <sub>I</sub> = - 18 mA | - 1.5   |       | - 1.5   |       | V    |
| V <sub>OH</sub>   | 'LS590 Q                   | V <sub>CC</sub> = MIN,<br>V <sub>IL</sub> = MAX                             | V <sub>IH</sub> = 2 V,                             | I <sub>OH</sub> = - 1 mA | 2.4     | 3.2   |         |       | V    |
|                   | I <sub>OH</sub> = - 2.6 mA |   |  |                          |         | 2.4   | 3.1     |       |      |
|                   | I <sub>OH</sub> = - 1 mA   |   |  | 2.4                      | 3.2     | 2.4   | 3.2     |       |      |
| I <sub>OH</sub>   | 'LS591 Q                   | V <sub>CC</sub> = MIN,<br>V <sub>IL</sub> = MAX                             | V <sub>IH</sub> = 2 V,<br>V <sub>OH</sub> = 5.5 V, | 0.1                      |         | 0.1   |         | mA    |      |
| V <sub>OL</sub>   | Q                          | V <sub>CC</sub> = MIN,<br>V <sub>IL</sub> = MAX                             | V <sub>IH</sub> = 2 V,                             | I <sub>OL</sub> = 12 mA  | 0.25    | 0.4   | 0.25    | 0.4   | V    |
|                   | I <sub>OL</sub> = 24 mA    |   |  |                          |         | 0.35  | 0.5     |       |      |
|                   | RCO                        |   |  | I <sub>OL</sub> = 8 mA   | 0.25    | 0.4   | 0.25    | 0.4   |      |
|                   |                            |   |  | I <sub>OL</sub> = 16 mA  |         |       | 0.35    | 0.5   |      |
| I <sub>OZH</sub>  | 'LS590 Q                   | V <sub>CC</sub> = MAX,<br>V <sub>O</sub> = 2.7 V                            | V <sub>IH</sub> = 2 V,<br>V <sub>IL</sub> = MAX,   | 20                       |         | 20    |         | μA    |      |
| I <sub>OZL</sub>  | 'LS590 Q                   | V <sub>CC</sub> = MAX,<br>V <sub>O</sub> = 0.4 V                            | V <sub>IH</sub> = 2 V,<br>V <sub>IL</sub> = MAX,   | - 20                     |         | - 20  |         | μA    |      |
| I <sub>I</sub>    |                            |   | V <sub>CC</sub> = MAX,                             | V <sub>I</sub> = 7 V     | 0.1     |       | 0.1     |       | mA   |
| I <sub>IH</sub>   |                            |   | V <sub>CC</sub> = MAX,                             | V <sub>I</sub> = 2.7 V   | 20      |       | 20      |       | μA   |
| I <sub>IL</sub>   | CCK                        | V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V                               |  |                          | - 0.8   |       | - 0.8   |       | mA   |
|                   | All others                 |   |  |                          | - 0.2   |       | - 0.2   |       |      |
| I <sub>OS</sub> § | 'LS590 Q                   | V <sub>CC</sub> = MAX, V <sub>O</sub> = 0 V                                 |  |                          | - 30    | - 130 | - 30    | - 130 | mA   |
|                   | RCO                        |   |  |                          | - 20    | - 100 | - 20    | - 100 |      |
| I <sub>CC</sub>   | 'LS590                     | V <sub>CC</sub> = MAX,<br>All possible inputs grounded,<br>All outputs open |  | I <sub>CCH</sub>         | 33      | 55    | 33      | 55    | mA   |
|                   |                            |   |  | I <sub>CCL</sub>         | 44      | 65    | 44      | 65    |      |
|                   |                            |   |  | I <sub>CCZ</sub>         | 46      | 65    | 46      | 65    |      |
|                   | 'LS591                     |   |  | I <sub>CCH</sub>         | 35      | 55    | 35      | 55    |      |
|                   |                            |   |  | I <sub>CCL</sub>         | 42      | 65    | 42      | 65    |      |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at  $V_{CC} = 5 \text{ V.}, T_A = 25^\circ\text{C}$

§ Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

switching characteristics,  $V_{CC} = 5 \text{ V.}, T_A = 25^\circ\text{C}$  (see note 3)

| PARAMETER        | FROM<br>(INPUT)          | TO<br>(OUTPUT)   | TEST CONDITIONS                                | 'LS590 |     |     | 'LS591 |     |     | UNIT |
|------------------|--------------------------|------------------|--|--------|-----|-----|--------|-----|-----|------|
|                  |                          |                  |  | MIN    | TYP | MAX | MIN    | TYP | MAX |      |
| $f_{\text{max}}$ | RCK                      | Q                | $R_L = 667 \Omega, C_L = 45 \text{ pF}$        | 20     | 35  |     | 20     | 35  |     | MHz  |
| $t_{PLH}$        | CCK†                     | $\overline{RCO}$ | $R_L = 1 \text{ k}\Omega, C_L = 30 \text{ pF}$ | 14     | 22  |     | 16     | 24  |     | ns   |
| $t_{PHL}$        | CCK†                     | $\overline{RCO}$ |  | 20     | 30  |     | 25     | 38  |     | ns   |
| $t_{PLH}$        | $\overline{CCLR}\dagger$ | $\overline{RCO}$ |  | 30     | 45  |     | 32     | 48  |     | ns   |
| $t_{PLH}$        | RCK†                     | Q                | $R_L = 667 \Omega, C_L = 45 \text{ pF}$        | 12     | 18  |     | 25     | 38  |     | ns   |
| $t_{PHL}$        | RCK†                     | Q                |  | 22     | 33  |     | 28     | 42  |     | ns   |
| $t_{PZH}$        | $\overline{G}\dagger$    | Q                |  | 25     | 38  |     |        |     |     | ns   |
| $t_{PZL}$        | $\overline{G}\dagger$    | Q                |  | 30     | 45  |     |        |     |     | ns   |
| $t_{PHZ}$        | $\overline{G}\dagger$    | Q                | $R_L = 667 \Omega, C_L = 5 \text{ pF}$         | 20     | 30  |     |        |     |     | ns   |
| $t_{PLZ}$        | $\overline{G}\dagger$    | Q                |  | 25     | 38  |     |        |     |     | ns   |
| $t_{PLH}$        | $\overline{G}\dagger$    | Q                | $R_L = 667 \Omega, C_L = 45 \text{ pF}$        |        |     |     | 34     | 50  |     | ns   |
| $t_{PHL}$        | $\overline{G}\dagger$    | Q                |  |        |     |     | 32     | 48  |     | ns   |

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

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**PACKAGING INFORMATION**

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup> | Lead/Ball Finish | MSL Peak Temp <sup>(3)</sup> |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 5962-87517012A   | ACTIVE                | LCCC         | FK              | 20   | 1           | TBD                     | POST-PLATE       | N / A for Pkg Type           |
| 5962-8751701EA   | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42 SNPB         | N / A for Pkg Type           |
| 5962-8751701EA   | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42 SNPB         | N / A for Pkg Type           |
| 5962-8751701FA   | ACTIVE                | CFP          | W               | 16   | 1           | TBD                     | A42              | N / A for Pkg Type           |
| 5962-8751701FA   | ACTIVE                | CFP          | W               | 16   | 1           | TBD                     | A42              | N / A for Pkg Type           |
| SN54LS590J       | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42 SNPB         | N / A for Pkg Type           |
| SN54LS590J       | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42 SNPB         | N / A for Pkg Type           |
| SN74LS590D       | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590D       | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590DE4     | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590DE4     | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590DR      | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590DR      | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590DRE4    | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590DRE4    | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590N       | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| SN74LS590N       | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| SN74LS590N3      | OBSOLETE              | PDIP         | N               | 16   |             | TBD                     | Call TI          | Call TI                      |
| SN74LS590N3      | OBSOLETE              | PDIP         | N               | 16   |             | TBD                     | Call TI          | Call TI                      |
| SN74LS590NE4     | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| SN74LS590NE4     | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| SN74LS590NSR     | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590NSR     | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590NSRE4   | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590NSRE4   | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SNJ54LS590FK     | ACTIVE                | LCCC         | FK              | 20   | 1           | TBD                     | POST-PLATE       | N / A for Pkg Type           |
| SNJ54LS590FK     | ACTIVE                | LCCC         | FK              | 20   | 1           | TBD                     | POST-PLATE       | N / A for Pkg Type           |
| SNJ54LS590J      | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42 SNPB         | N / A for Pkg Type           |
| SNJ54LS590J      | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42 SNPB         | N / A for Pkg Type           |
| SNJ54LS590W      | ACTIVE                | CFP          | W               | 16   | 1           | TBD                     | A42              | N / A for Pkg Type           |
| SNJ54LS590W      | ACTIVE                | CFP          | W               | 16   | 1           | TBD                     | A42              | N / A for Pkg Type           |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

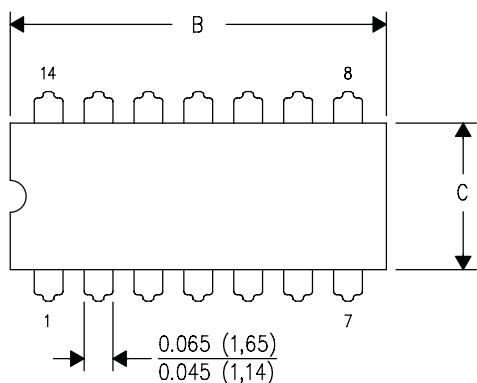
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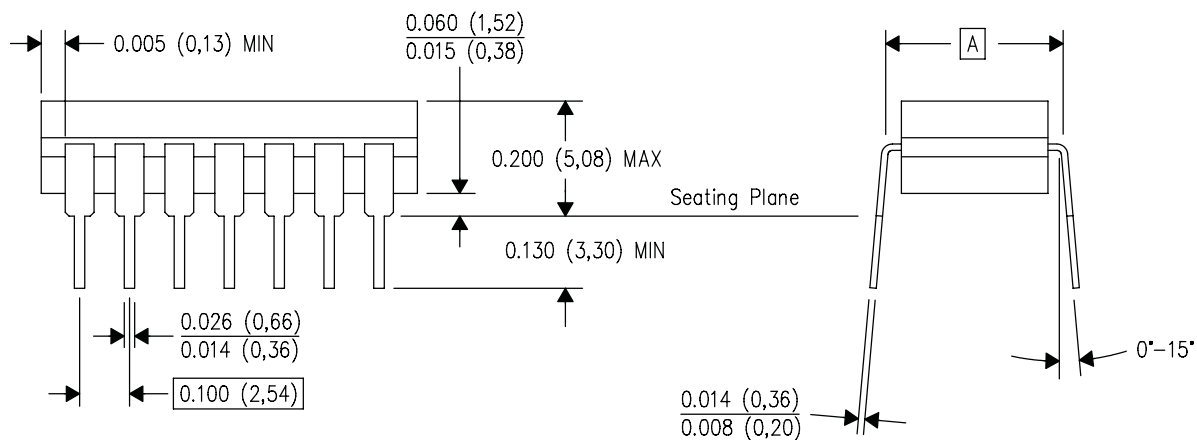
J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



| PINS **<br>DIM | 14                     | 16                     | 18                     | 20                     |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A              | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX          | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN          | —                      | —                      | —                      | —                      |
| C MAX          | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN          | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |



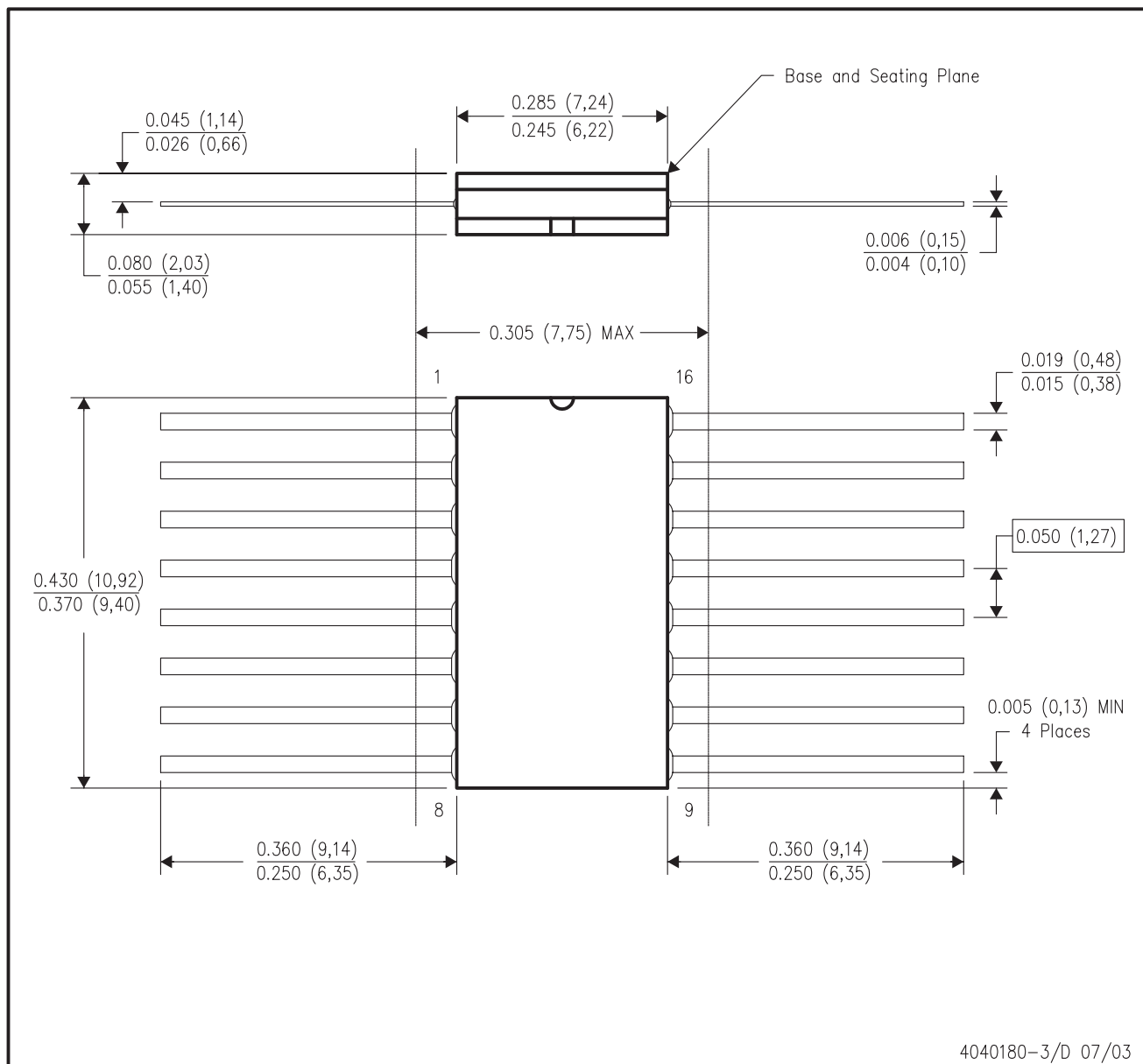
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



## W (R-GDFP-F16)

## CERAMIC DUAL FLATPACK

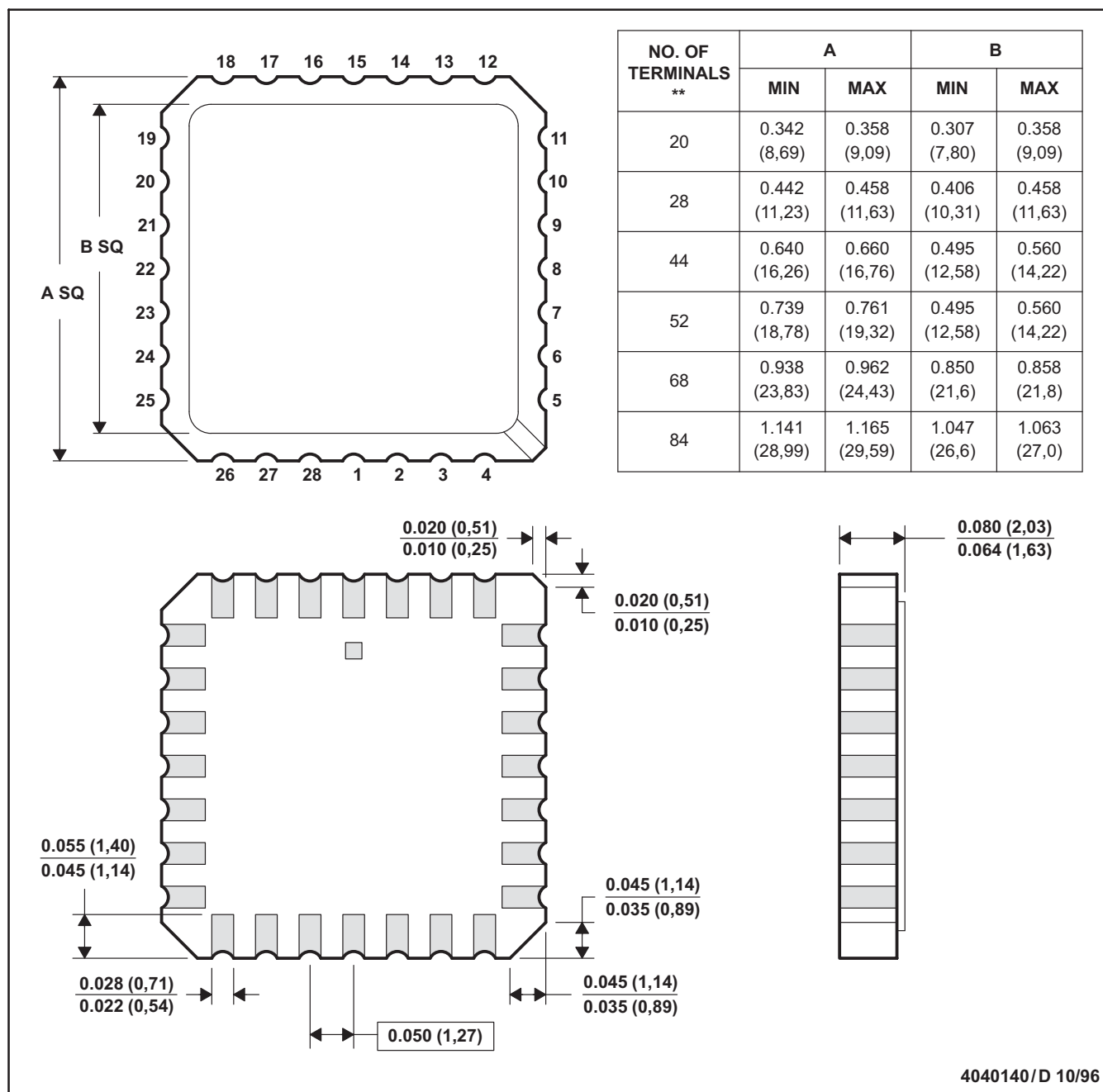


- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only.
  - Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

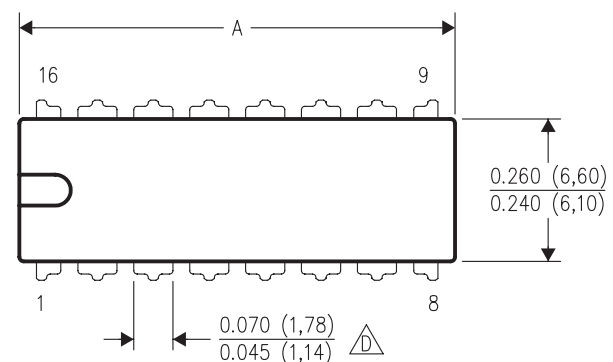


- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - The terminals are gold plated.
  - Falls within JEDEC MS-004

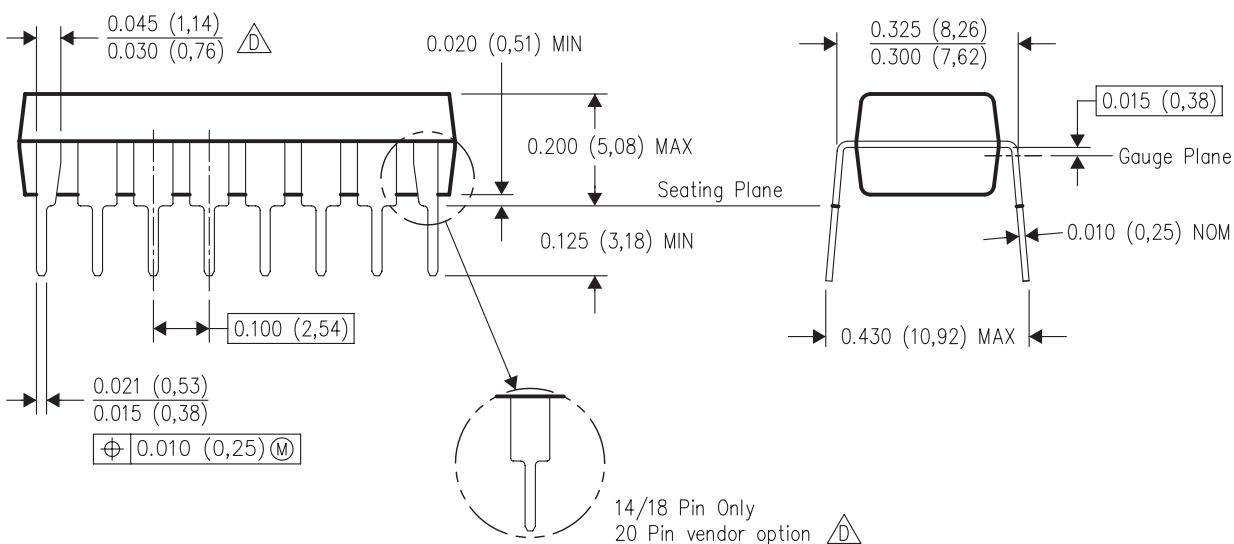
## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



| PINS **             | 14               | 16               | 18               | 20               |
|---------------------|------------------|------------------|------------------|------------------|
| DIM                 |                  |                  |                  |                  |
| A MAX               | 0.775<br>(19,69) | 0.775<br>(19,69) | 0.920<br>(23,37) | 1.060<br>(26,92) |
| A MIN               | 0.745<br>(18,92) | 0.745<br>(18,92) | 0.850<br>(21,59) | 0.940<br>(23,88) |
| MS-001<br>VARIATION | AA               | BB               | AC               | AD               |

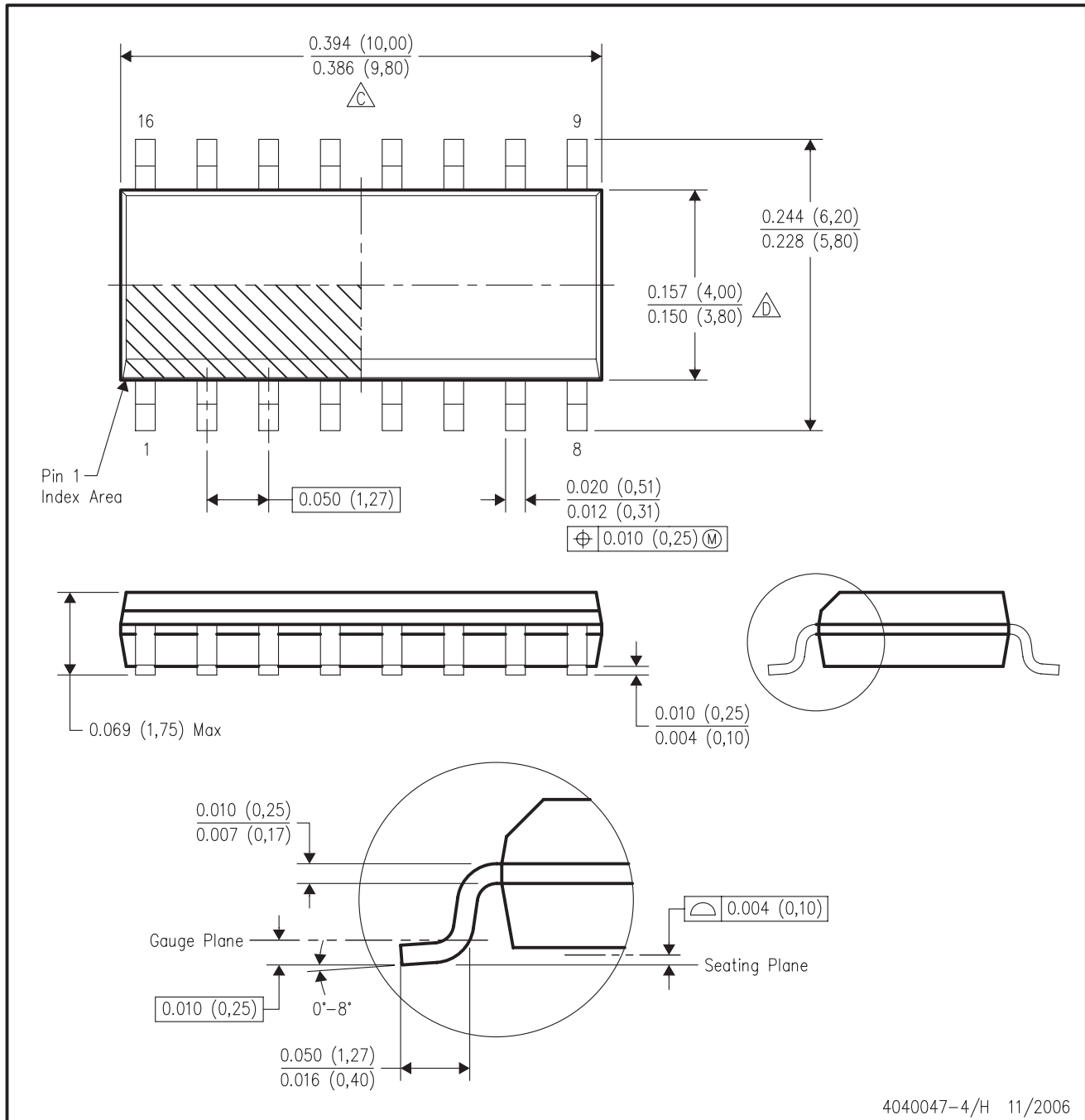


4040049/E 12/2002

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

## D (R-PDSO-G16)

## PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/H 11/2006

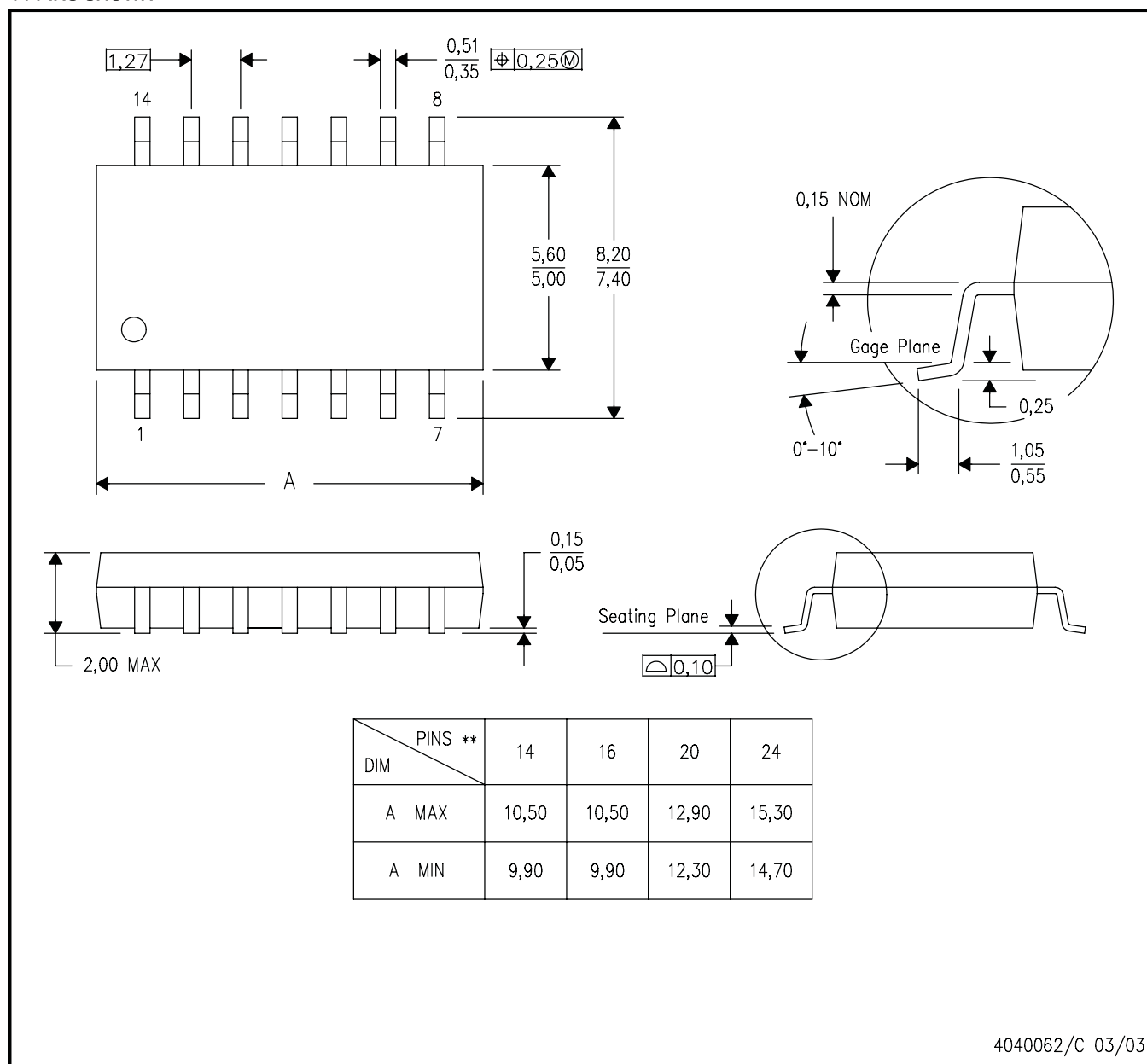
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AC.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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**PACKAGING INFORMATION**

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup> | Lead/Ball Finish | MSL Peak Temp <sup>(3)</sup> |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 5962-87517012A   | ACTIVE                | LCCC         | FK              | 20   | 1           | TBD                     | POST-PLATE       | N / A for Pkg Type           |
| 5962-8751701EA   | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42 SNPB         | N / A for Pkg Type           |
| 5962-8751701EA   | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42 SNPB         | N / A for Pkg Type           |
| 5962-8751701FA   | ACTIVE                | CFP          | W               | 16   | 1           | TBD                     | A42              | N / A for Pkg Type           |
| 5962-8751701FA   | ACTIVE                | CFP          | W               | 16   | 1           | TBD                     | A42              | N / A for Pkg Type           |
| SN54LS590J       | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42 SNPB         | N / A for Pkg Type           |
| SN54LS590J       | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42 SNPB         | N / A for Pkg Type           |
| SN74LS590D       | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590D       | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590DE4     | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590DE4     | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590DR      | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590DR      | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590DRE4    | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590DRE4    | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590N       | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| SN74LS590N       | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| SN74LS590N3      | OBSOLETE              | PDIP         | N               | 16   |             | TBD                     | Call TI          | Call TI                      |
| SN74LS590N3      | OBSOLETE              | PDIP         | N               | 16   |             | TBD                     | Call TI          | Call TI                      |
| SN74LS590NE4     | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| SN74LS590NE4     | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| SN74LS590NSR     | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590NSR     | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590NSRE4   | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74LS590NSRE4   | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SNJ54LS590FK     | ACTIVE                | LCCC         | FK              | 20   | 1           | TBD                     | POST-PLATE       | N / A for Pkg Type           |
| SNJ54LS590FK     | ACTIVE                | LCCC         | FK              | 20   | 1           | TBD                     | POST-PLATE       | N / A for Pkg Type           |
| SNJ54LS590J      | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42 SNPB         | N / A for Pkg Type           |
| SNJ54LS590J      | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42 SNPB         | N / A for Pkg Type           |
| SNJ54LS590W      | ACTIVE                | CFP          | W               | 16   | 1           | TBD                     | A42              | N / A for Pkg Type           |
| SNJ54LS590W      | ACTIVE                | CFP          | W               | 16   | 1           | TBD                     | A42              | N / A for Pkg Type           |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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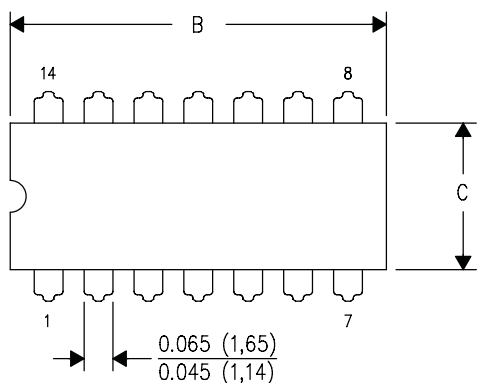
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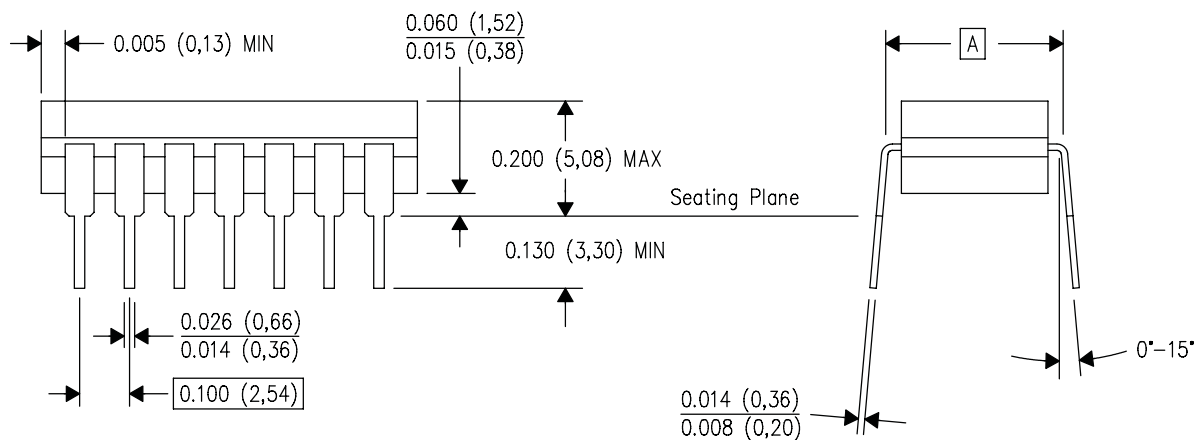
J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14                     | 16                     | 18                     | 20                     |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A             | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX         | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN         | —                      | —                      | —                      | —                      |
| C MAX         | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN         | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |

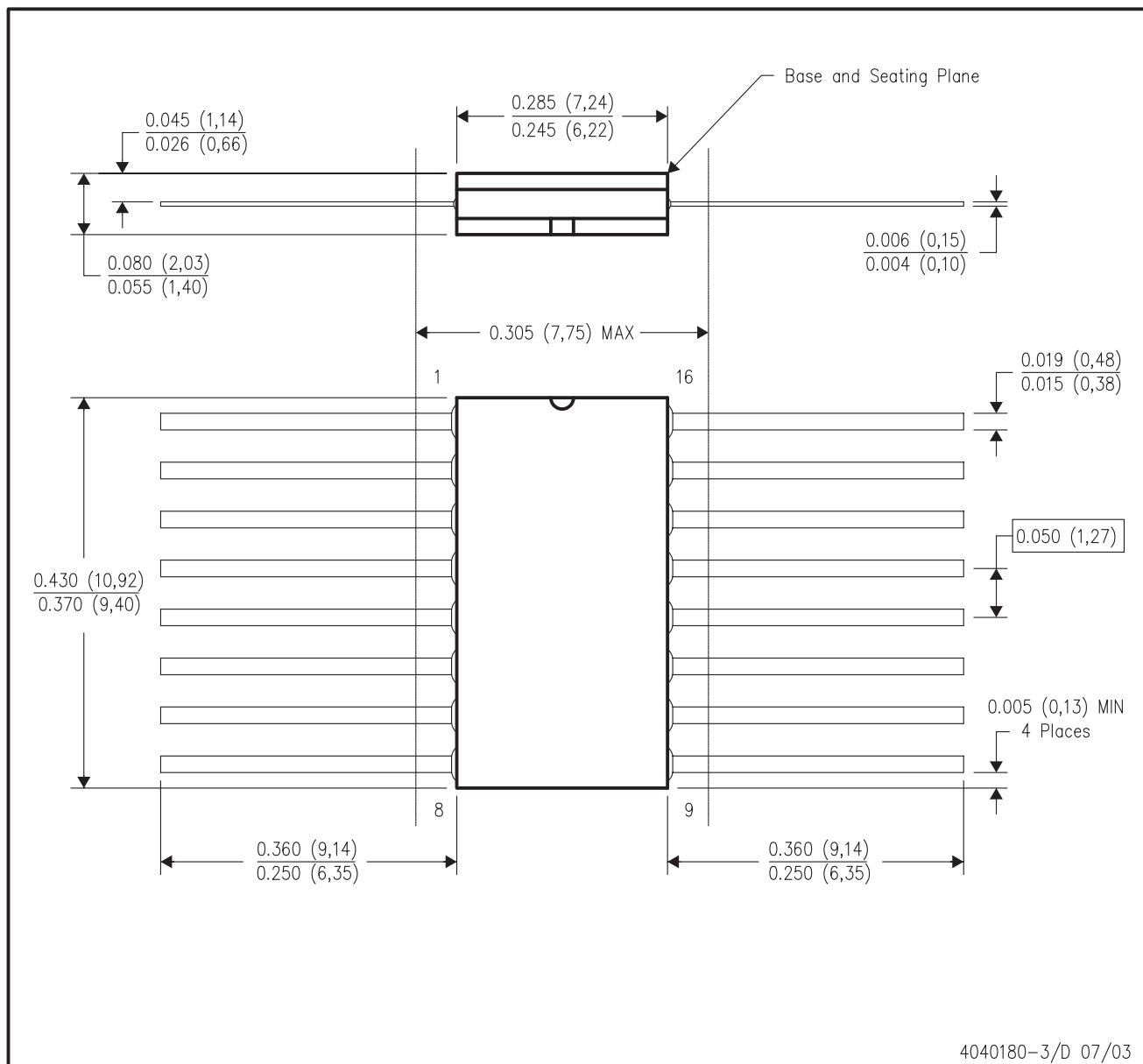


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK

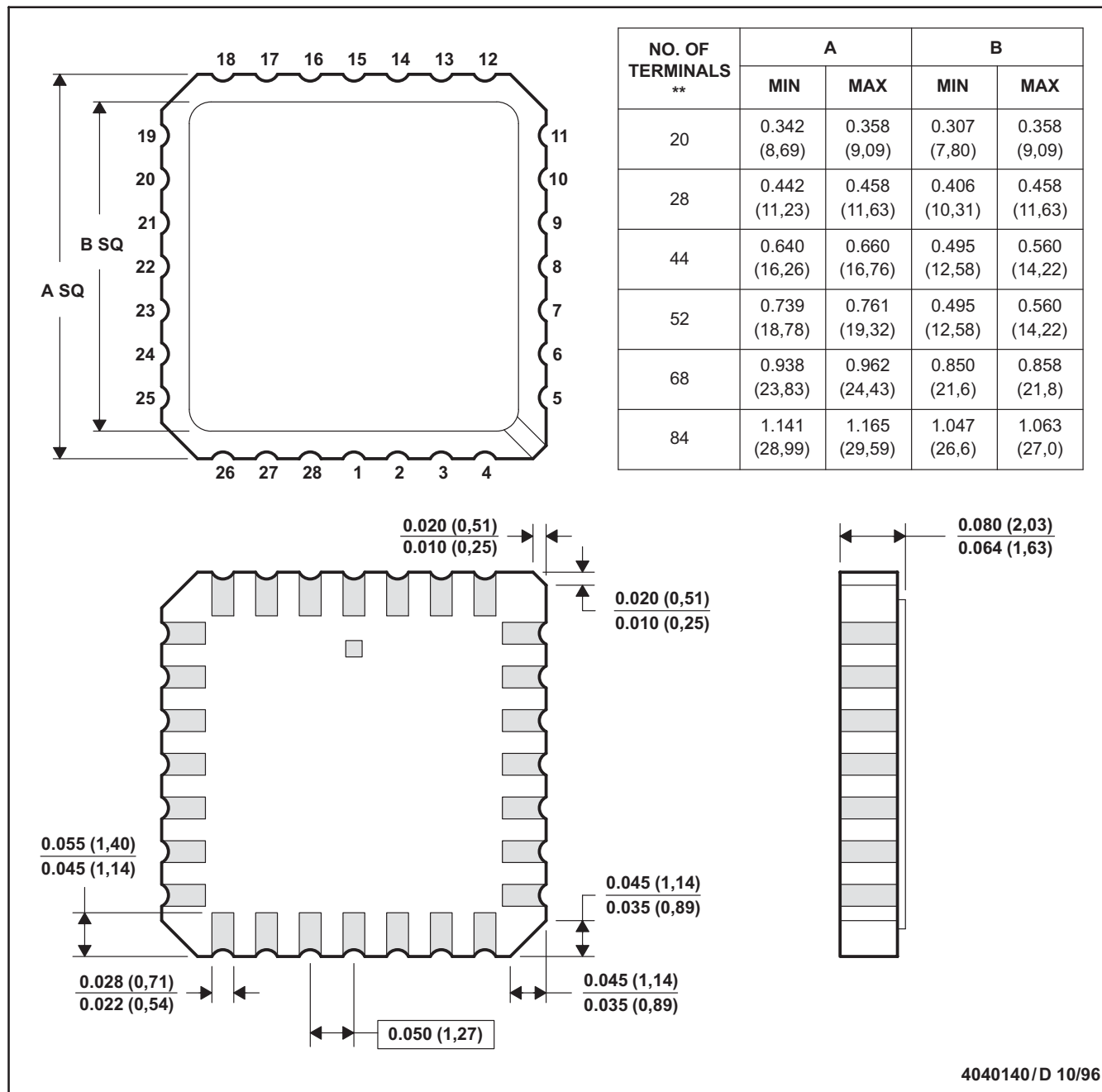


- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only.
  - Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

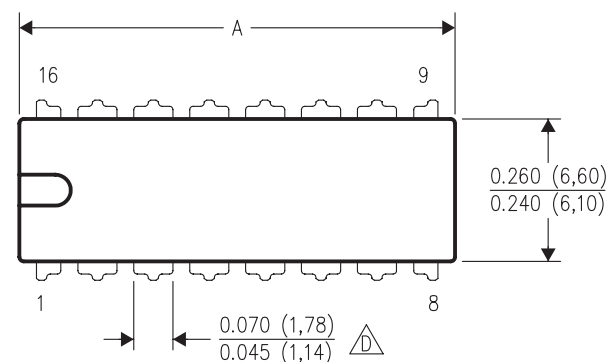


- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - The terminals are gold plated.
  - Falls within JEDEC MS-004

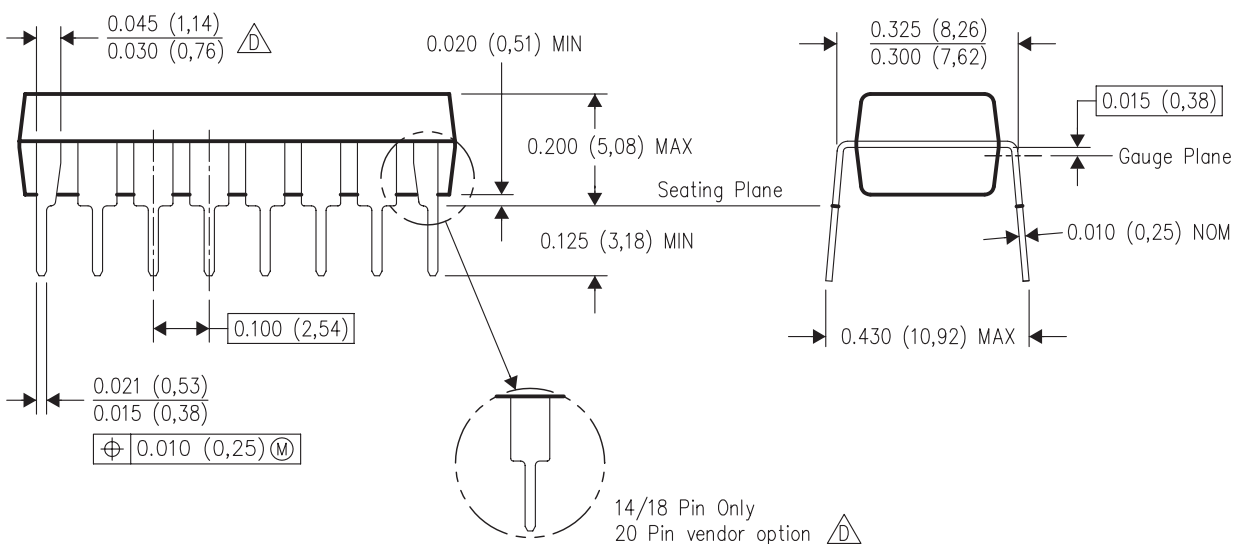
## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



| PINS **             | 14               | 16               | 18               | 20               |
|---------------------|------------------|------------------|------------------|------------------|
| DIM                 |                  |                  |                  |                  |
| A MAX               | 0.775<br>(19,69) | 0.775<br>(19,69) | 0.920<br>(23,37) | 1.060<br>(26,92) |
| A MIN               | 0.745<br>(18,92) | 0.745<br>(18,92) | 0.850<br>(21,59) | 0.940<br>(23,88) |
| MS-001<br>VARIATION | AA               | BB               | AC               | AD               |

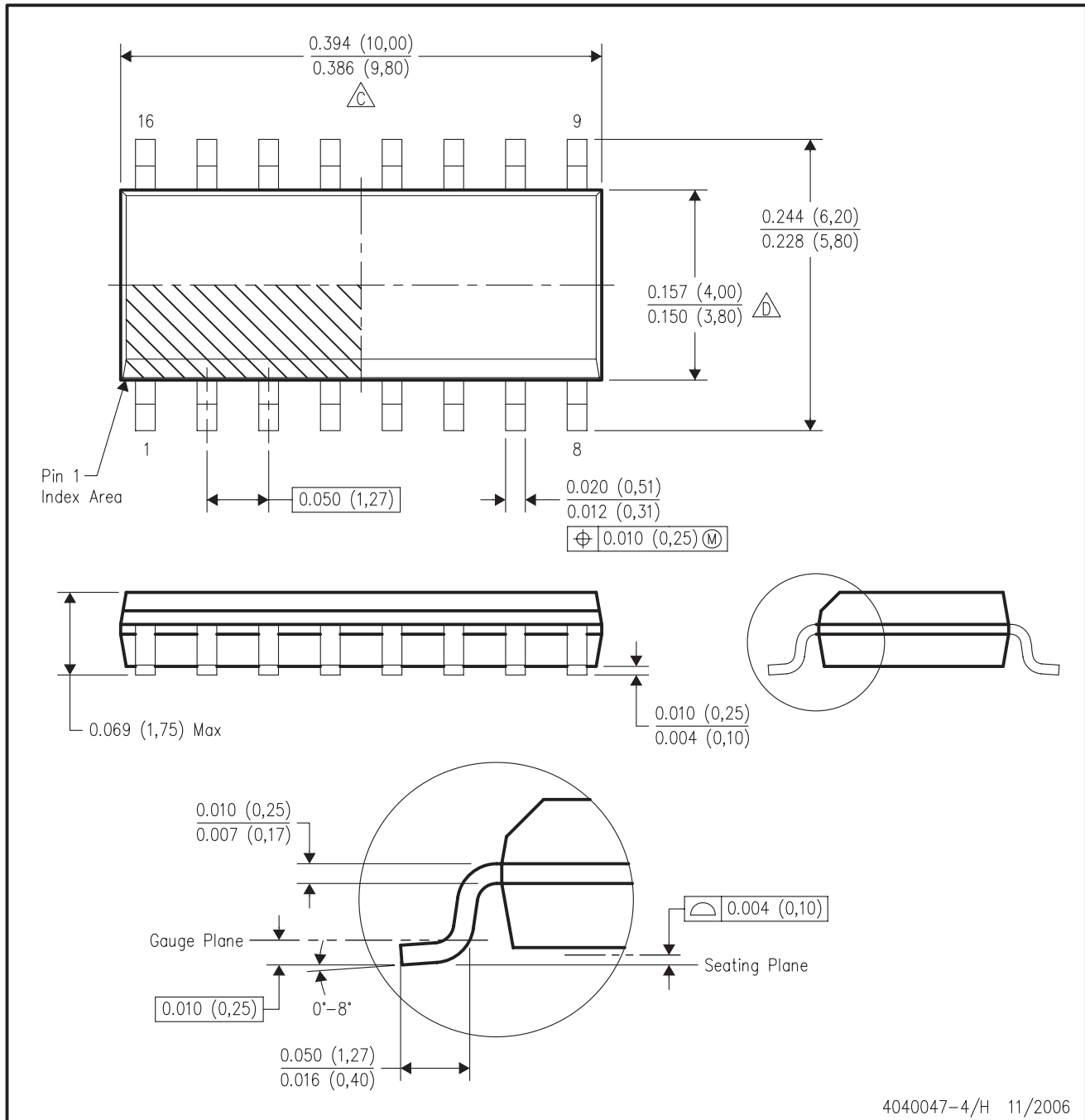


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

## D (R-PDSO-G16)

## PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/H 11/2006

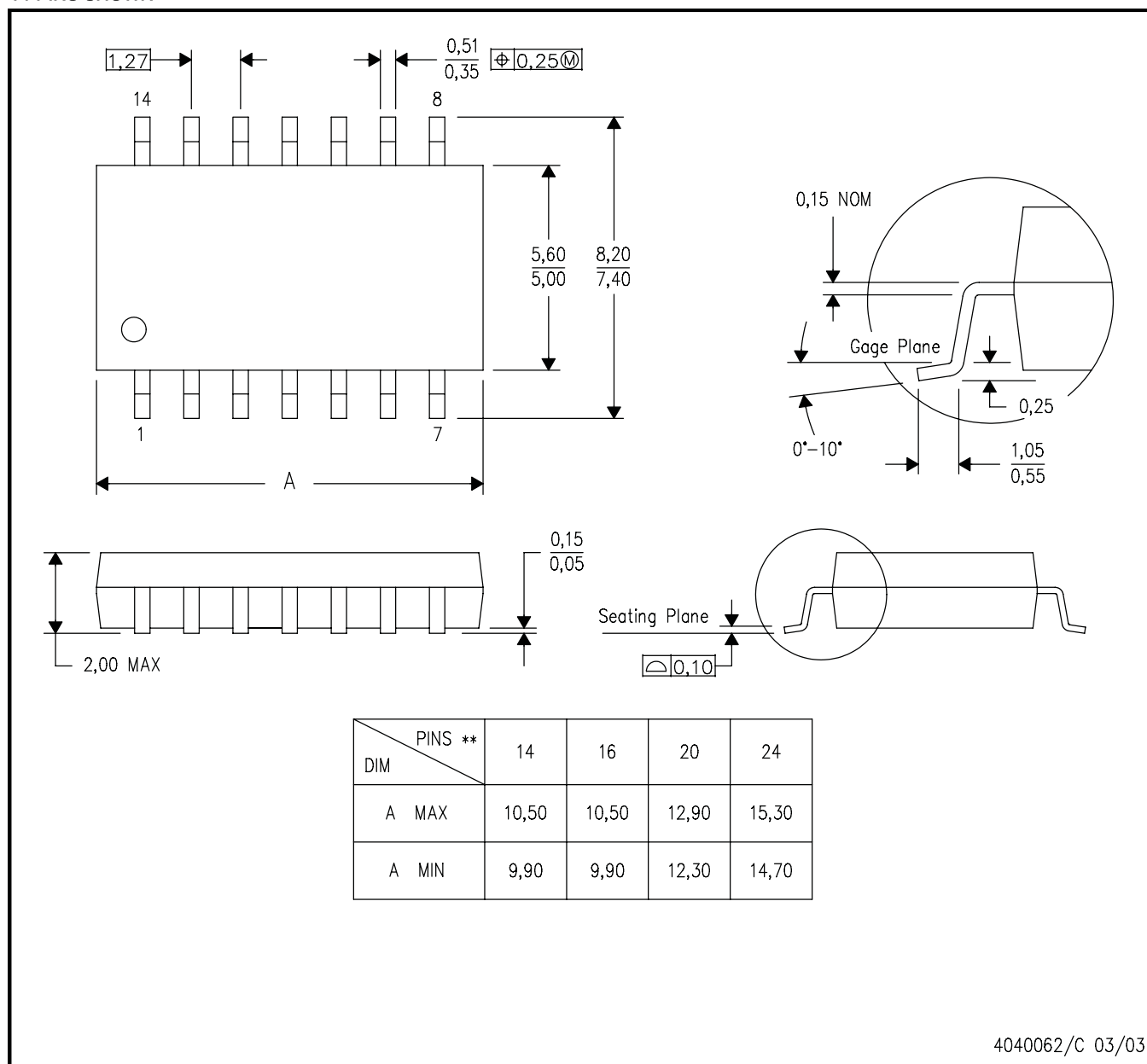
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AC.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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